2N6387, 2N6388

2N6388 is a Preferred Device

Plastic Medium-Power Silicon Transistors

These devices are designed for general−purpose amplifier and low−speed switching applications.

Features

- High DC Current Gain − h_{FE} = 2500 (Typ) @ I_C = 4.0 Adc
- Collector−Emitter Sustaining Voltage − @ 100 mAdc
  $V_{CEO(sus)}$ = 60 Vdc (Min) − 2N6387
  = 80 Vdc (Min) − 2N6388
- Low Collector−Emitter Saturation Voltage −
  $V_{CE(sat)}$ = 2.0 Vdc (Max) @ I_C
  = 5.0 Adc − 2N6387, 2N6388
- Monolithic Construction with Built−In Base−Emitter Shunt Resistors
- TO−220AB Compact Package
- Pb−Free Packages are Available*

ON Semiconductor®

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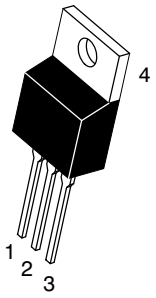
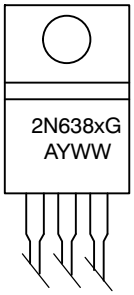
DARLINGTON NPN SILICON POWER TRANSISTORS 8 AND 10 AMPERES 65 WATTS, 60 − 80 VOLTS

MARKING DIAGRAM



TO−220AB
CASE 221A
STYLE 1



2N638x = Device Code
x = 7 or 8
G = Pb−Free Package
A = Assembly Location
Y = Year
WW = Work Week

MAXIMUM RATINGS (Note 1)

Rating		Symbol	Value	Unit
Collector−Emitter Voltage	2N6387 2N6388	V_{CEO}	60 80	Vdc
Collector−Base Voltage	2N6387 2N6388	V_{CB}	60 80	Vdc
Emitter−Base Voltage		V_{EB}	5.0	Vdc
Collector Current − Continuous − Peak		I_C	10 15	Adc
Base Current		I_B	250	mAdc
Total Power Dissipation @ T_C = 25°C Derate above 25°C		P_D	65 0.52	W W/°C
Total Power Dissipation @ T_A = 25°C Derate above 25°C		P_D	2.0 0.016	W W/°C
Operating and Storage Junction, Temperature Range		T_J, T_{stg}	−65 to +150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	1.92	°C/W
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	62.5	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Indicates JEDEC Registered Data.

ORDERING INFORMATION

Device	Package	Shipping
2N6387	TO−220AB	50 Units / Rail
2N6387G	TO−220AB (Pb−Free)	50 Units / Rail
2N6388	TO−220AB	50 Units / Rail
2N6388G	TO−220AB (Pb−Free)	50 Units / Rail

Preferred devices are recommended choices for future use and best overall value.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

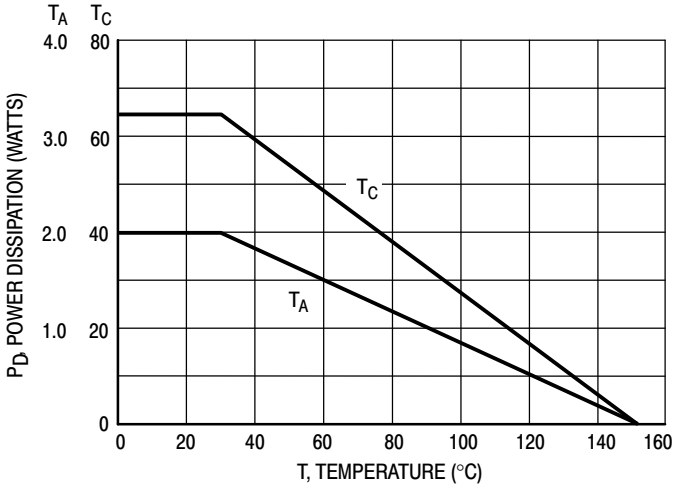


Figure 1. Power Derating

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted) (Note 2)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector−Emitter Sustaining Voltage (Note 3) (I_C = 200 mAdc, I_B = 0)	 2N6387 2N6388	$V_{CEO(sus)}$	 60 80	 − −	Vdc
Collector Cutoff Current (V_{CE} = 60 Vdc, I_B = 0) (V_{CE} = 80 Vdc, I_B = 0)	 2N6387 2N6388	I_{CEO}	 − −	 1.0 1.0	mAdc
Collector Cutoff Current (V_{CE} = 60 Vdc, $V_{EB(off)}$ = 1.5 Vdc) (V_{CE} − 80 Vdc, $V_{EB(off)}$ = 1.5 Vdc) (V_{CE} = 60 Vdc, $V_{EB(off)}$ = 1.5 Vdc, T_C = 125°C) (V_{CE} = 80 Vdc, $V_{EB(off)}$ = 1.5 Vdc, T_C = 125°C)	 2N6387 2N6388 2N6387 2N6388	I_{CEX}	 − − − −	 300 300 3.0 3.0	μAdc mAdc
Emitter Cutoff Current (V_{BE} = 5.0 Vdc, I_C = 0)		I_{EBO}	−	5.0	mAdc
ON CHARACTERISTICS (Note 3)					
DC Current Gain (I_C = 5.0 Adc, V_{CE} = 3.0 Vdc) (I_C = 1 0 Adc, V_{CE} = 3.0 Vdc)	 2N6387, 2N6388 2N6387, 2N6388	h_{FE}	 1000 100	 20,000 −	−
Collector−Emitter Saturation Voltage (I_C = 5.0 Adc, I_B = 0.01 Adc) (I_C = 10 Adc, I_B = 0.1 Adc)	 2N6387, 2N6388 2N6387, 2N6388	$V_{CE(sat)}$	 − −	 2.0 3.0	Vdc
Base−Emitter On Voltage (I_C = 5.0 Adc, V_{CE} = 3.0 Vdc) (I_C = 10 Adc, V_{CE} = 3.0 Vdc)	 2N6387, 2N6388 2N6387, 2N6388	$V_{BE(on)}$	 − −	 2.8 4.5	Vdc
DYNAMIC CHARACTERISTICS					
Small−Signal Current Gain (I_C = 1.0 Adc, V_{CE} = 5.0 Vdc, f_{test} = 1.0 MHz)		$\|h_{fe}\|$	20	−	−
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)		C_{ob}	−	200	pF
Small−Signal Current Gain (I_C = 1.0 Adc, V_{CE} = 5.0 Vdc, f = 1.0 kHz)		h_{fe}	1000	−	−

2. Indicates JEDEC Registered Data.
3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

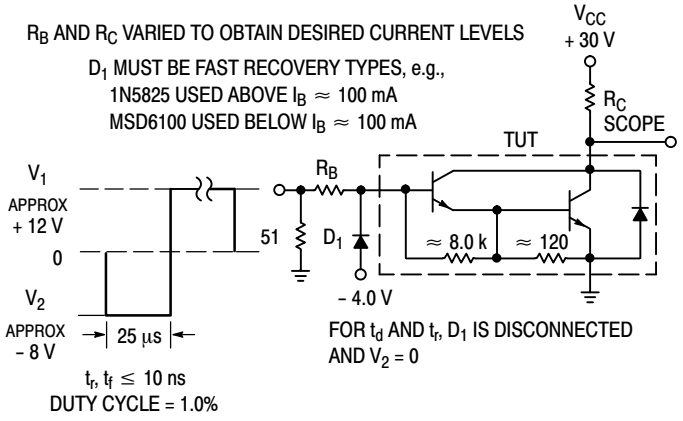


Figure 2. Switching Times Test Circuit

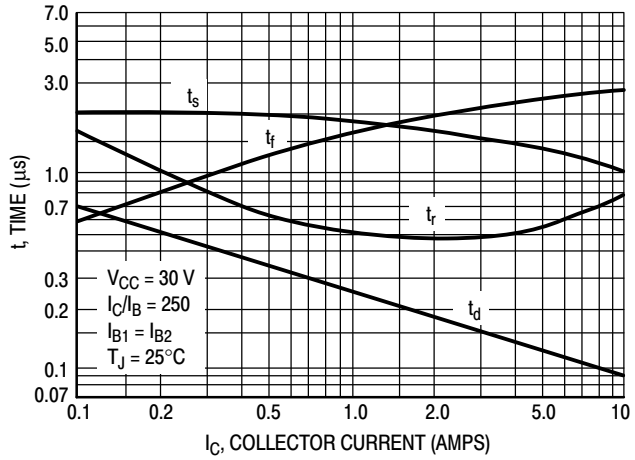


Figure 3. Switching Times

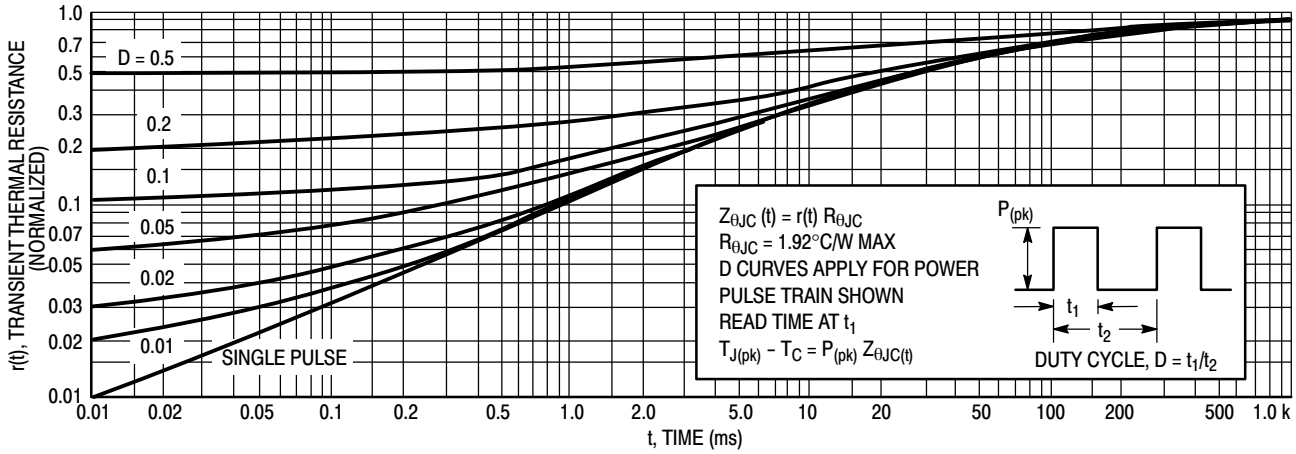


Figure 4. Thermal Response

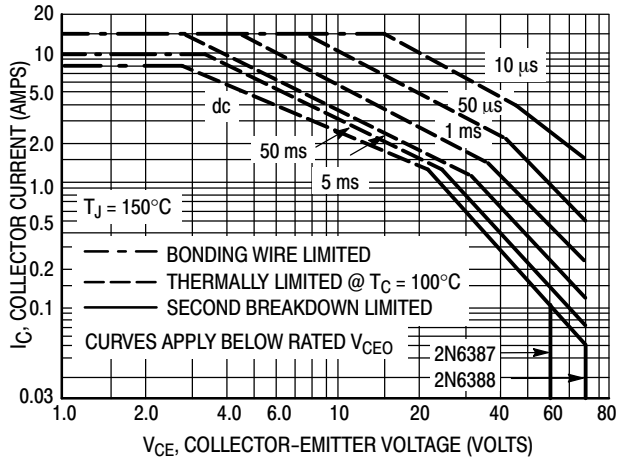


Figure 5. Active-Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C − V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)}$ = 150°C; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)}$ < 150°C. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown

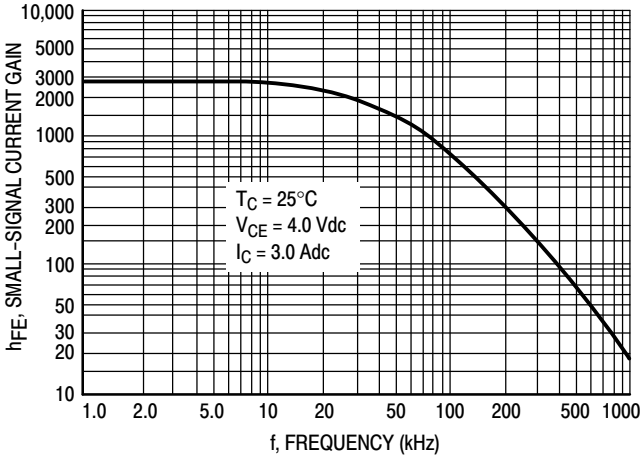


Figure 6. Small−Signal Current Gain

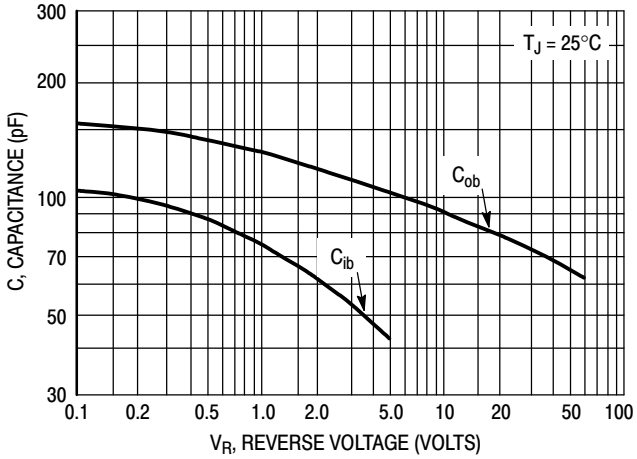


Figure 7. Capacitance

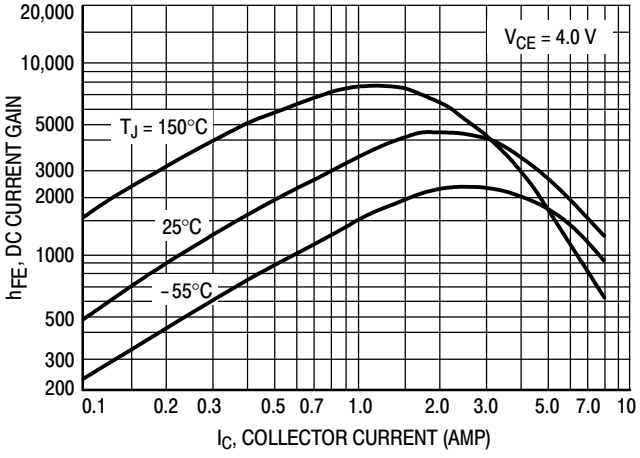


Figure 8. DC Current Gain

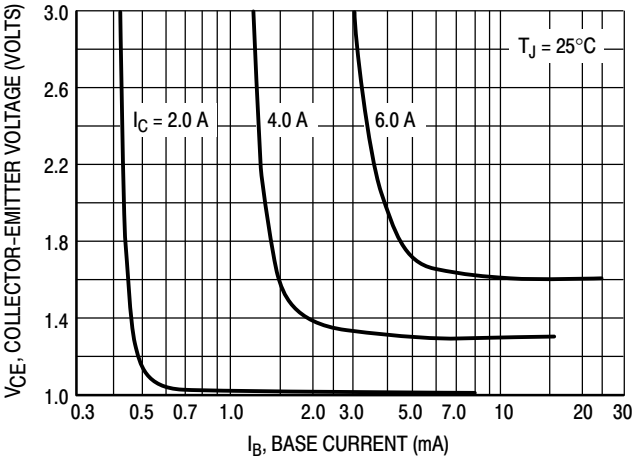


Figure 9. Collector Saturation Region

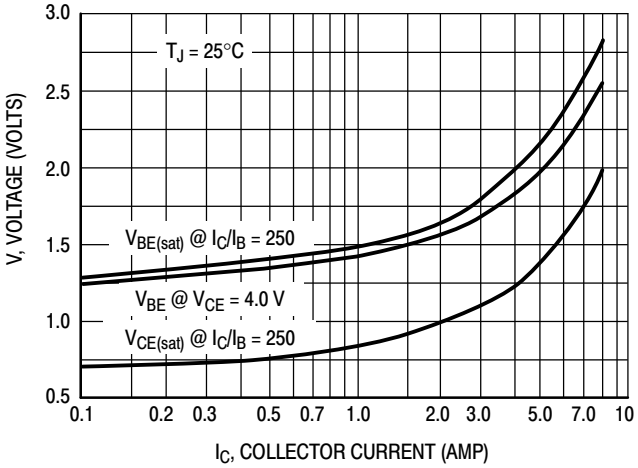


Figure 10. “On” Voltages

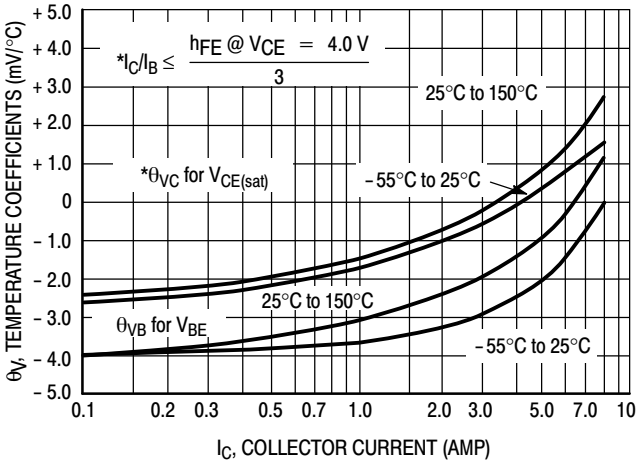


Figure 11. Temperature Coefficients

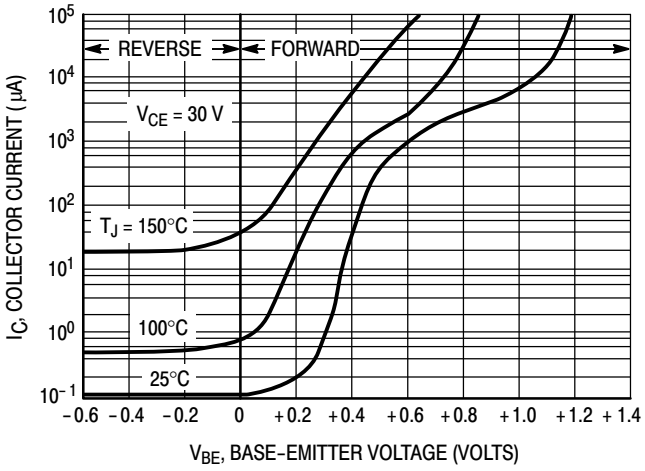


Figure 12. Collector Cut−Off Region

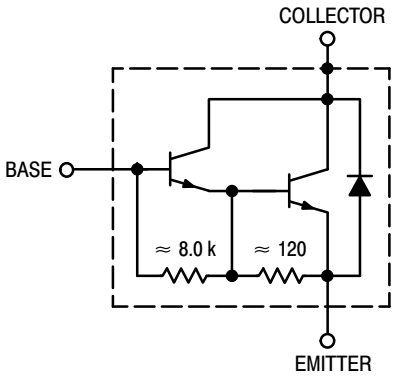
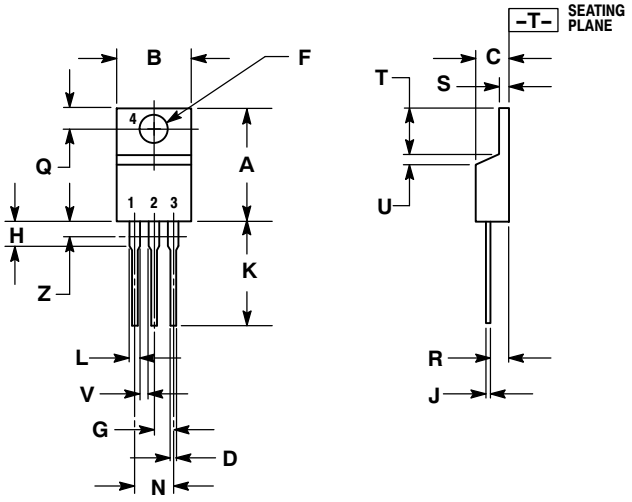


Figure 13. Darlington Schematic

PACKAGE DIMENSIONS

TO−220
CASE 221A−09
ISSUE AE



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

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